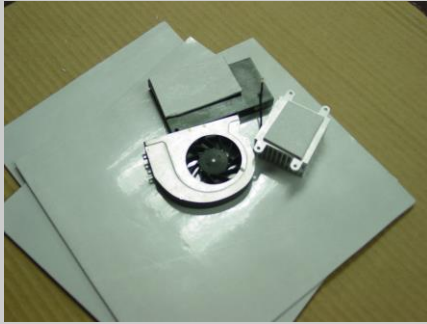


THERMALLY CONDUCTIVE GAP FILLER 3.0W/m-K

Features and Benefits

- 3.0W/m-K thermal conductivity
- Moderate compressibility
- Cost effective
- Electrically isolating



Typical Applications

- Cooling component to the chassis, frame, or other type of heat spreader
- Mass storage device
- Heat pipe assemblies
- RDRAM memory modules
- Motor control
- Telecommunication hardware

Optional Configurations

- Fibreglass reinforcements are recommended for $\leq 0.03''$
- Adhesive coatings are optional
- Aluminium lamination is optional
- Can be die-cut into specific dimensions

E-Fill 8100 Spec 02 is a performance-improved derivative of the original E-Fill 8100 gap pad. This special feature is benefited from a revised metal oxide filler matrix. It is electrically non-conductive and conforms to UL94 V0 standard.

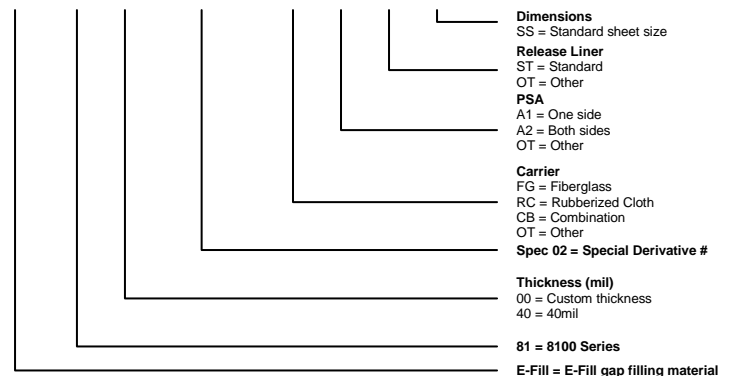
Properties	E-Fill 8100 Spec 02	Test Method
Construction & Composition	Soft silicone elastomer	—
Color	Grey	Visual
Thickness Range /inch (mm)	0.01"~0.20" (0.254~5.08) in 0.01" (0.254) increments	—
Standard Sheet Size	12" x 16"	—
Density /g.cm ⁻³	2.98	—
Hardness /Shore 00	60	ASTM D2240
UL Flammability Rating	Conforms to UL94 V0 Standard	—
Temperature Range /°C	-40~200°C	—
Thermal Conductivity W.m ⁻¹ .K ⁻¹	3.0	ASTM D5470 (modified)
Breakdown Voltage /V	>3000 (Thickness $\geq 0.30\text{mm}$) >5000 (Thickness $\geq 0.75\text{mm}$)	ASTM D149
Shelf Life	24 months	—

Please contact us for other special requirements

Carrier Treatment	Criteria
Fiber Glass (FG)	Compulsory for $\leq 0.012''$ (0.3mm)
Rubberized Cloth (RC)	Not Recommended
Pressure Sensitive Adhesive (PSA)	Not Recommended
Detachable Adhesive (DA)	Not Recommended
Aluminum Foil (AL)	Not Recommended
Kapton (PI)	Not Recommended
Talc treatment (DAT)	Not Recommended

Product Code and Descriptions

E-Fill 81 XX Spec 02 -XX -XX -XX -XX



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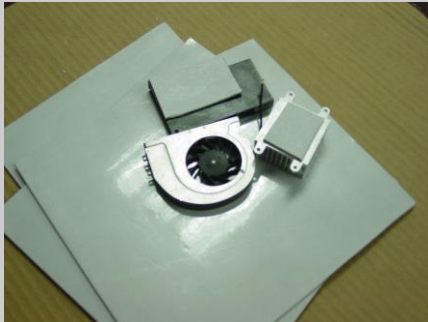
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产品特点

- 导热率 3.0W/m-K
- 中等压缩比
- 低成本
- 电绝缘



一般应用

- 高速大容量存储设备
- RDRAM 记忆模组
- 热管组件
- 底盘，框架或其他散热组件
- 电机控制器
- 无线通信硬件

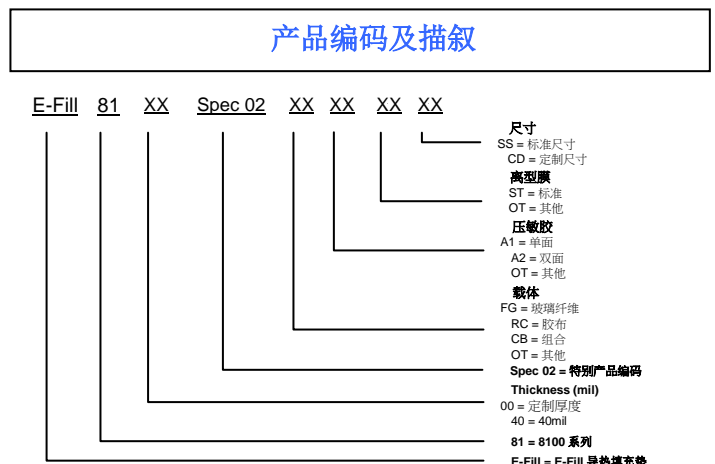
其他配置

- 产品厚度 ≤ 0.03"，建议使用玻璃纤维强化
- 可选择胶粘剂涂层
- 可选择铝箔强化
- 可模切成特定尺寸

E-Fill 8100 Spec 02 是基于 E-Fill 8100 改良而成的。新的氧化金属填充物料配方使 E-Fill 8100 Spec 02 的导热性能得到大幅的提升。E-Fill 8100 Spec 02 是电绝缘体而且达到 UL94V0 防火要求。

一般特性	E-Fill 8100 Spec 02	测试方法
结构及主要成分	硅树脂弹性体	—
颜色	灰色	目测
厚度 /inch (mm)	0.01"~0.20" (0.254~5.08) 以 0.01" (0.254)为基本增量单位	—
标准片材尺寸	12" x 16"	—
密度 /g.cm ⁻³	2.98	—
硬度 /Shore 00	60	ASTM D2240
UL 燃烧等级	达到 UL94 V0 标准	—
使用温度 /°C	-40~200°C	—
导热率 W.m ⁻¹ .K ⁻¹	3.0	ASTM D5470 (modified)
击穿电压/V	>3000 (厚度 ≥ 0.30mm) >5000 (厚度 ≥ 0.75mm)	ASTM D149
有效期/Months	24	—
如对产品有特殊要求，请联络我们		

载体	标准
玻璃纤维 (FG)	厚度 ≤ 0.012" (0.3mm) 必须使用
胶布 (RC)	不建议使用
压敏胶 (PSA)	不建议使用
不粘胶 (DA)	不建议使用
铝箔 (AL)	不建议使用
聚酰亚胺膜 (PI)	不建议使用
滑石粉处理 (DAT)	不建议使用



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